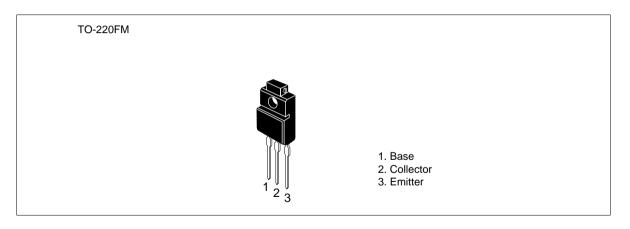
# Silicon NPN Triple Diffused

# HITACHI

#### Application

Low frequency high voltage power amplifier TV vertical deflection output complementary pair with 2SB1530

#### Outline





## **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

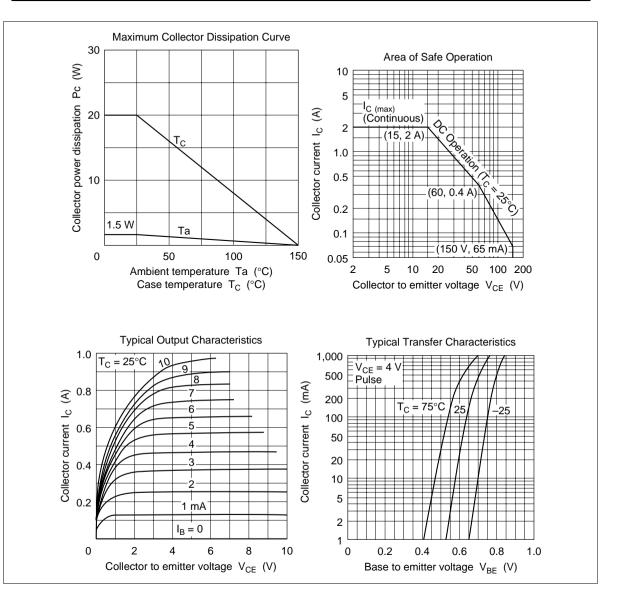
Symbol	Ratings	Unit	
V <sub>CBO</sub>	200	V	
V <sub>CEO</sub>	150	V	
V <sub>EBO</sub>	6	V	
Ι <sub>c</sub>	2	А	
I <sub>C(peak)</sub>	5	А	
Pc	1.5	W	
P <sub>c</sub> * <sup>1</sup>	20		
Tj	150	°C	
Tstg	-45 to +150	°C	
	$     V_{CBO}     V_{CEO}     V_{EBO}     I_{C}     I_{C(peak)}     \underline{P_{C}}     P_{C}^{*1}     Tj     Tj   $	$     \begin{array}{cccc}         V_{CBO} & 200 \\         V_{CEO} & 150 \\         V_{EBO} & 6 \\         I_{C} & 2 \\         I_{C(peak)} & 5 \\         \hline         P_{C} & 1.5 \\         P_{C}^{*1} & 20 \\         Tj & 150 \\         \end{array} $	

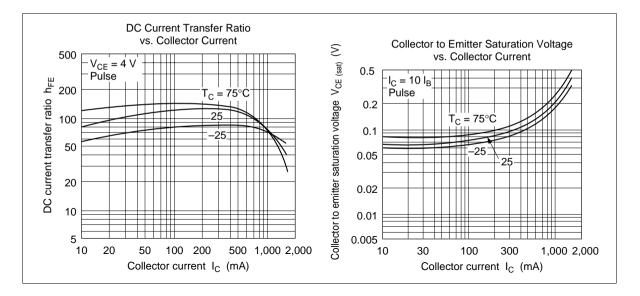
Note: 1. Value at  $T_c = 25^{\circ}C$ .

#### **Electrical Characteristics** (Ta = 25°C)

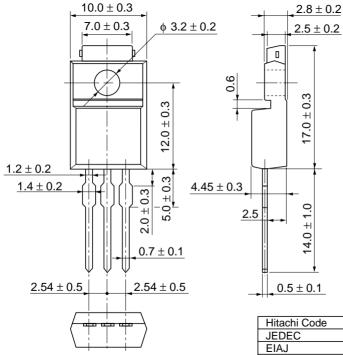
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	150	_	_	V	$I_c = 50 \text{ mA}, \text{ R}_{\text{BE}} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	_	_	V	$I_{\rm E} = 5$ mA, $I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>			1	μΑ	$V_{CB} = 120 \text{ V}, \text{ I}_{E} = 0$
DC current transfer ratio	$h_{FE1}^{*1}$	60		320		$V_{ce} = 4 \text{ V}, \text{ I}_{c} = 50 \text{ mA}$
	h <sub>FE2</sub>	60				$V_{ce} = 10 \text{ V}, I_c = 500 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	—	3.0	V	$I_{c} = 500 \text{ mA}, I_{B} = 50 \text{ mA}^{*2}$
Base to emitter voltage	V <sub>BE</sub>	_		1.0	V	$V_{ce} = 4 \text{ V}, \text{ I}_{c} = 50 \text{ mA}$
Notes: 1. The 2SD2337 is gro	ouped by h	FE1 as fo	llows.			
2. Pulse test.						
B C D						

60 to 120 100 to 200 160 to 320

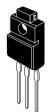




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Unit: mm



Hitachi Code	TO-220FM
JEDEC	
EIAJ	Conforms
Weight (reference value)	1.8 g

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